

SN5426, SN54LS26, SN7426, SN74LS26
QUADRUPLE 2-INPUT
HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES

DECEMBER 1983—REVISED MARCH 1988

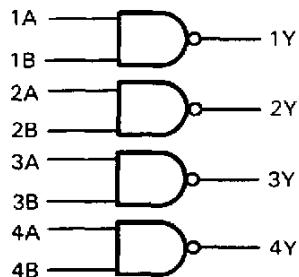
- For Driving Low-Threshold-Voltage MOS Inputs

description

These 2-input open-collector NAND gates feature high-output voltage ratings for interfacing with low-threshold-voltage MOS logic circuits or other 12-volt systems. Although the output is rated to withstand 15 volts, the V_{CC} terminal is connected to the standard 5-volt source.

The SN5426 and SN54LS26 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN7426 and SN74LS26 are characterized for operation from 0°C to 70°C .

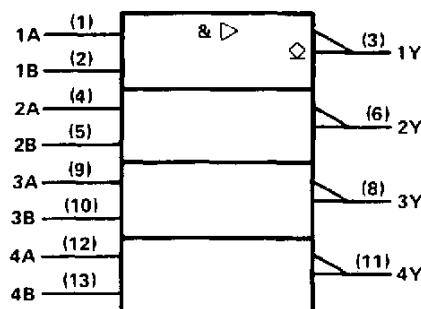
logic diagram



positive logic

$$Y = \overline{AB}$$

logic symbol†

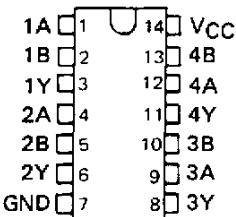


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

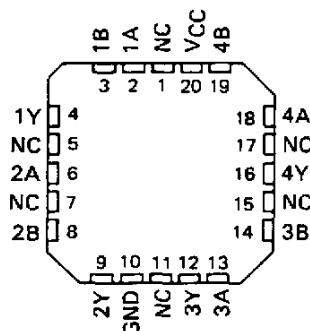
SN5426 . . . J PACKAGE
 SN54LS26 . . . J OR W PACKAGE
 SN7426 . . . N PACKAGE
 SN74LS26 . . . D OR N PACKAGE

(TOP VIEW)



SN54LS26 . . . FK PACKAGE

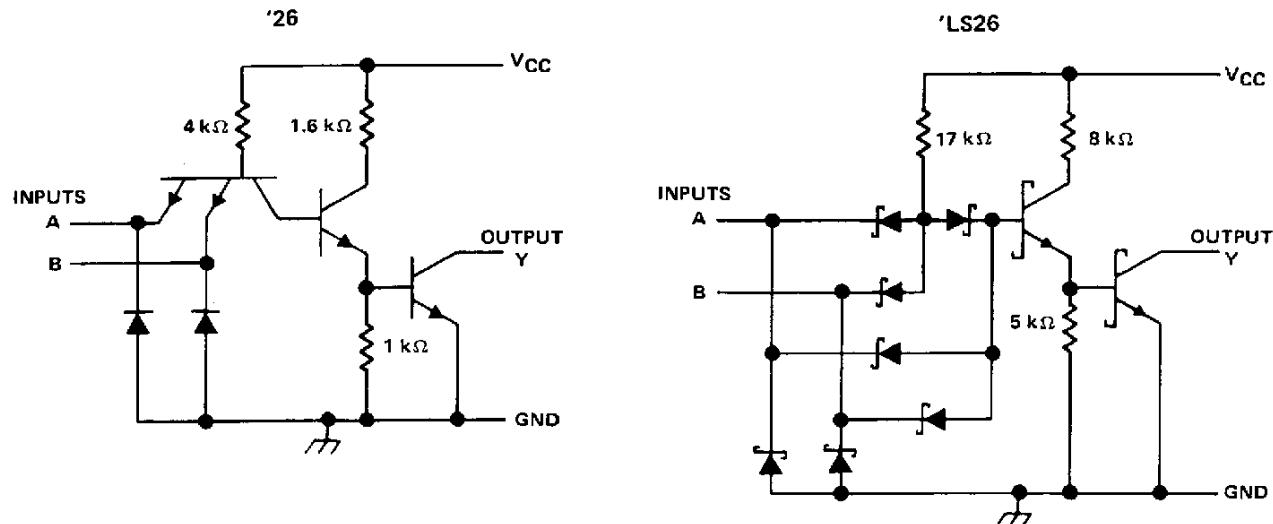
(TOP VIEW)



NC - No internal connection

SN5426, SN54LS26, SNSN7426, SN74LS26
QUADRUPLE 2-INPUT
HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES

schematics



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage: '26	5.5 V
'LS26	7 V
Operating free-air temperature: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54LS26, SN74LS26
QUADRUPLE 2-INPUT
HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES

recommended operating conditions

	SN54LS26			SN74LS26			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage				0.7		0.8	V
V _{OH} High-level output voltage				15		15	V
I _{OL} Low-level output current				4		8	mA
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]	SN54LS26			SN74LS26			UNIT
		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	
V _{IK}	V _{CC} = MIN, I _I = -18 mA				-1.5		-1.5	V
I _{OH}	V _{CC} = MIN, V _{IL} = MAX, V _{OH} = 12 V				50		50	μA
	V _{CC} = MIN, V _{IL} = MAX, V _{OH} = 15 V				1		1	mA
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 4 mA		0.25	0.4	0.25	0.4		V
	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 8 mA				0.35	0.5		
I _I	V _{CC} = MAX, V _I = 7 V				0.1		0.1	mA
I _{IH}	V _{CC} = MAX, V _{IH} = 2.7 V				20		20	μA
I _{IL}	V _{CC} = MAX, V _{IL} = 0.4 V				-0.4		-0.4	mA
I _{CCH}	V _{CC} = MAX, V _I = 0		0.8	1.6	0.8	1.6		mA
I _{CCL}	V _{CC} = MAX, V _I = 4.5 V		2.4	4.4	2.4	4.4		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	A or B	Y	R _L = 2 kΩ, C _L = 15 pF	17	32	ns	
t _{PHL}				15	28	ns	

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN5426, SN7426
QUADRUPLE 2-INPUT
HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES

recommended operating conditions

	SN5426			SN7426			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.8			0.8	V
V _{OH} High-level output voltage			15			15	V
I _{OL} Low-level output current			16			16	mA
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]	SN5426			SN7426			UNIT
		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	
V _{IK}	V _{CC} = MIN, I _I ≈ -12 mA			-1.5			-1.5	V
I _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V, V _{OH} = 12 V						50	μA
	V _{CC} = MIN, V _{IL} = 0.7 V, V _{OH} = 12 V			50				
	V _{CC} = MIN, V _{IL} = 0.8 V, V _{OH} = 15 V						1	mA
	V _{CC} = MIN, V _{IL} = 0.7 V, V _{OH} = 15 V			1				
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 16 mA			0.4			0.4	V
I _I	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.4 V			40			40	μA
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			-1.6			-1.6	mA
I _{CCH}	V _{CC} = MAX, V _I = 0			4	8		4	mA
I _{CCL}	V _{CC} = MAX, V _I = 4.5 V			12	22		12	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at V_{CC} = 5 V, T_A = 25°C.

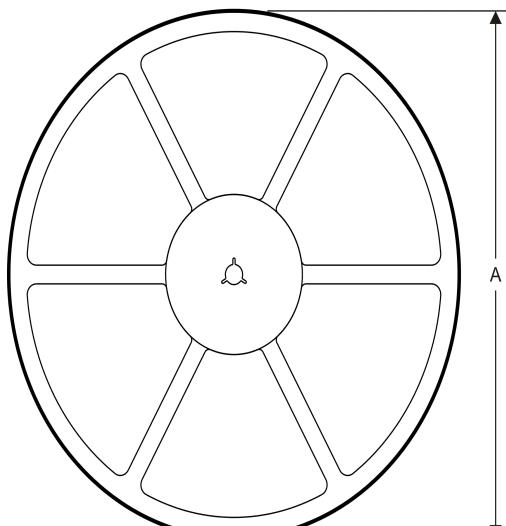
switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	A or B	Y	R _L = 1 kΩ, C _L = 15 pF	16	24		ns
t _{PHL}				11	17		ns

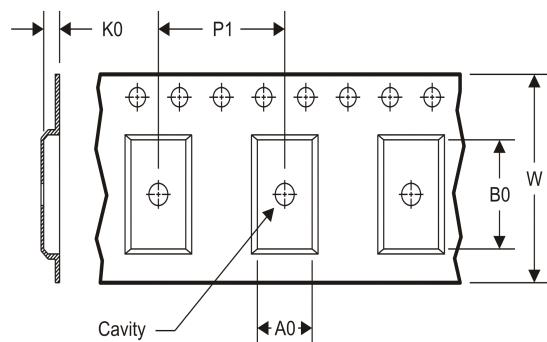
NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

TAPE AND REEL INFORMATION

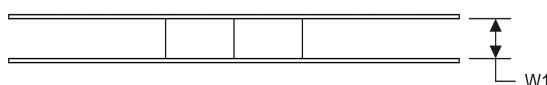
REEL DIMENSIONS



TAPE DIMENSIONS



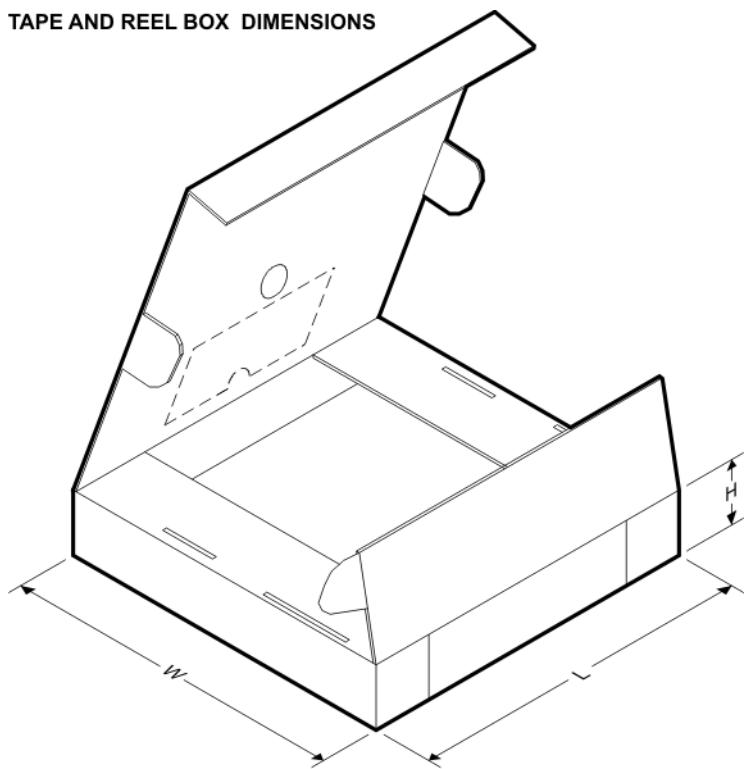
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers



TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS26DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS26DR	SOIC	D	14	2500	367.0	367.0	38.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2012, Texas Instruments Incorporated